
Tin Whisker Growth Testing Position Statement

Fair-Rite Products Corp. has decided to forego the time-consuming test procedures necessary to measure the likelihood of tin whisker growth on the connections of our lead-free components. Instead, Fair-Rite has adopted industry-accepted precautions to prevent the formation of tin whisker growth on tin coated wires and terminations. These precautions have been implemented on all lead-free wires and terminations by including a nickel barrier layer and a matte 100% tin coating surface layer.

Signed:



RJ Stevens
Director of Quality
July 10, 2025